Special Issue

3D Computer Vision and 3D Reconstruction

Message from the Guest Editors

The Special Issue aims to explore the latest advancements and innovations in the field of 3D computer vision and 3D reconstruction techniques. The topics include, but are not limited to: (1) 3D information acquisition and processing; (2) 3D reconstruction methods; (3) computer vision; (4) deep learning for 3D systems; (5) emerging optical materials for 3D reconstruction.

Guest Editors

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Dr. Di Wang

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Deadline for manuscript submissions

31 December 2025

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About the Journal

Message from the Editor-in-Chief

Electronics is a multidisciplinary journal designed to appeal to a diverse audience of research scientists, practitioners, and developers in academia and industry. The journal is devoted to fast publication of latest technological breakthroughs, cutting-edge developments, and timely reviews of current and emerging technologies related to the broad field of electronics. Experimental and theoretical results are published as regular peer-reviewed articles or as articles within Special Issues guest-edited by leading experts in selected topics of interest.

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